

MANUFACTURER NAME & ADDRESS Dynamic Details Inc, Anaheim 1220 N. Simon Circle Anaheim, CA 92806	PLANT LOCATION Same	CAGE CODE: OBSG1 Contact: Mr. Rick Sylvain 714-688-7371 rsylvain@ddiglobal.com
CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION		
MIL-PRF31032/1 & MIL-PRF31032/2		QUALIFICATION LETTERS:
Max. Panel Size: 18" X 24" Max./Min. Board Thickness: 0.100" Max./Min. Through Hole Size: 0.045"/0.032" (drilled) Aspect Ratio: 3:1 Max. Number of Layers: 10 Minimum Conductor Width: 0.010" Minimum Conductor Spacing: 0.010" Part Mounting: THM only Rigid Base Material: GI: Woven E-glass, Epoxy Resin, Flame Resistant Finish System: HASL, ENIG Hole Preparation: Plasma Desmear, Plasma Etchback Copper Plating: Electroless & Electrodeposited Acid Copper Alternate Construction: Foil Lamination Solder Resist: Liquid Photo-imageable (LPI)		VQ-09-018147 (initial)

This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the

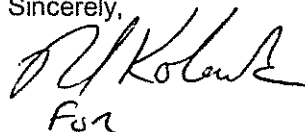
Visit us on the web at http://www.dscc.dla.mil/offices/sourcing_and_qualification

qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during PCI or CVI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. This letter acts as a letter of delegation in accordance with Chapter 1.4.1 of DLAD 5000.4 and VI.C.1.c of DLAR 4120.13 for your local Government QAR to survey your facility listed above for compliance, as necessary.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Jeffrey Ciesla, (614) 692-0624.

Sincerely,



For
JOSEPH GEMPERLINE
Chief
Sourcing and Qualifications Division

Visit us on the web at http://www.dscc.dla.mil/offices/sourcing_and_qualification